



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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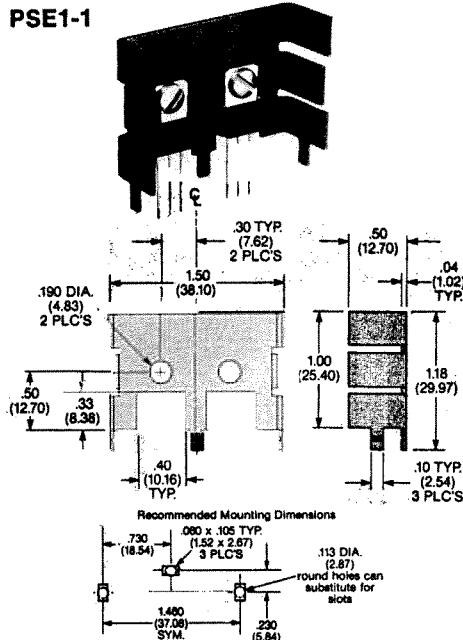
SECTION 2

HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

Stand-up, dual-mounted heat dissipators

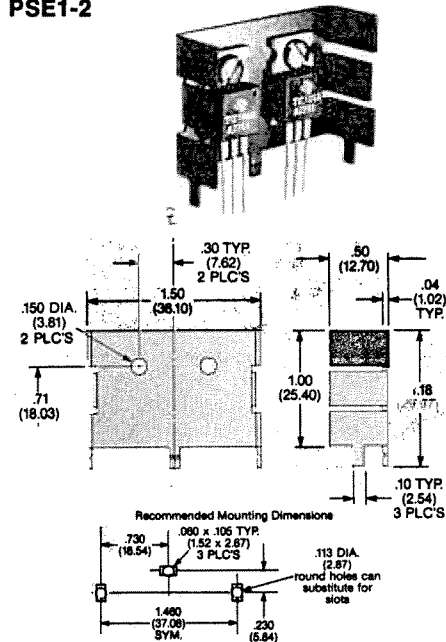
- Thermally matches two semiconductors within 2°C at equivalent power levels up to 9 watts per semiconductor, permitting paired semiconductors to function more nearly identical.
- Effective alternative to back-to-back semiconductor mounting; eliminates lead interferences.
- Minimizes board space requirements while providing effective heat dissipation.
- Bend relief notches on mounting tabs permit easy installation with no mounting hardware or special tools required.
- Each dissipator of this series is specifically designed for use with a particular transistor case type — performance and fit are optimized.

PSE1-1

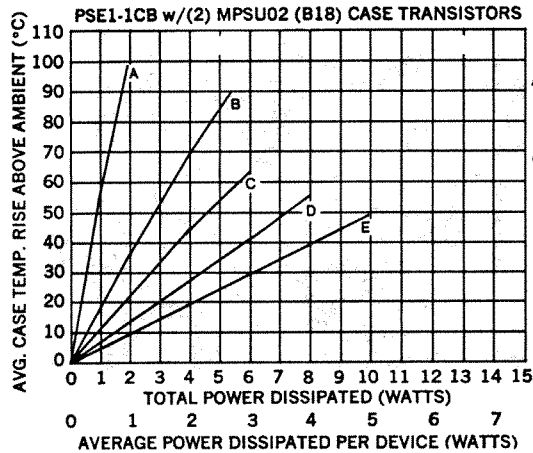


Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

PSE1-2



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

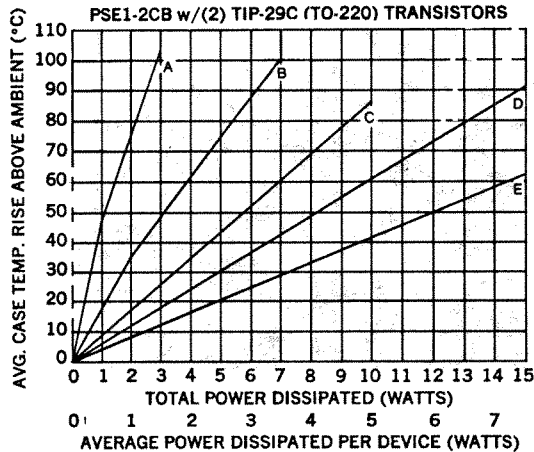
- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 1.9-2.3 °C/W w/Joint Compound.
- Derate 6.4 °C/watt per device for unplated part in natural convection only.
- Case Temperatures Match Within 2°C at equivalent power levels.

Ordering Information

| IERC PART NO. | | | | | Semiconductor Accommodated | Max. Weight (Grams) |
|---------------|-----------------------|--------------------|----------|------------------------------------|----------------------------|---------------------|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | Nickel | Black Coating with Solderable Tabs | | |
| PSE1-1U | PSE1-1CB | PSE1-1B | PSE1-1ND | PSE1-1TCB | Two Motorola Case 152s | 3.6 |

Note: See page Iv for other finishes.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 4.0 °C/watt per device for unplated part in natural convection only.
- Case Temperatures Match Within 2°C at equivalent power levels.

Ordering Information

| IERC PART NO. | | | | | Semiconductor Accommodated | Max. Weight (Grams) |
|---------------|-----------------------|--------------------|----------|------------------------------------|---------------------------------------|---------------------|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | Nickel | Black Coating with Solderable Tabs | | |
| PSE1-2U | PSE1-2CB | PSE1-2B | PSE1-2ND | PSE1-2TCB | Two TO-126s, Two TO-127s, Two TO-220s | 4.2 |

Note: See page Iv for other finishes.